

Sept. 30	Oct. 1 (Mon)	Oct. 2 (Tue)	Oct. 3 (Wed)	Oct. 4 (Thu)	Oct. 5 (Fri)
Conference Room: 3F Convention Hall Poster Room: 1F Multi-Purpose Hall COLA Office Room: 4F-404 (Oct.1-5), 3F-304 (Sept. 30-Oct.2)	8:45 ————— Opening Address 9:00 ————— I. Fundamentals of Laser Ablation D. D. Dlott M. Maltz-Knorr K. G. Nakamura S. Acquaviva	9:00 ————— IV. Nano Science / Nano Technology using Laser-Solid Interactions S. Iijima (Key Note) A. A. Puzos A. Gorbunov	9:00 ————— VII. fs-Laser Ablation & Applications H. Hosono E. G. Gamaly H. Misawa A. F. Semerok	9:00 ————— IX. Variety of Ultrashort Laser Ablation and Spectroscopy V. Margetic M. Hase D. R. Ermer M. Kurata-Nishimura	9:00 ————— XIII. Laser Plasma and Applications K. Kondo J. G. Lunney R. Dietsch
	10:30 ————— Coffee Break 11:00 ————— II. Fundamentals of Laser Ablation W. P. Hess M. Zeifman J. T. Dickinson N. M. Bulgakova 12:30 ————— Lunch Time 13:30 ————— Poster (I)	10:30 ————— Coffee Break 11:00 ————— V. Nano Science / Nano Technology using Laser-Solid Interactions S. Lee W. Marine M. S. El-Shall T. Makimura P. Leiderer 12:50 ————— Lunch Time 14:00 ————— Poster (II)	10:30 ————— Coffee Break 11:00 ————— VIII. Nano Science / Nano Technology & Nonthermal Effects F. Stietz H. Amasuga K. M. Beck 12:10 ————— 12:30 Bus Starts ! — Lunch Box Excursion	10:30 ————— Coffee Break 11:00 ————— X. Variety of Laser Ablation A. Vertes D. Anglos 11:50 ————— Lunch Time 13:30 ————— XI. Laser Ablation of Polymer / Organic Materials T. Lippert S. Georgiou N. Nishio H. Masuhara J. S. Horwitz 15:30 ————— Coffee Break 16:00 ————— XII. Pulsed Laser Deposition of Films E. Vasco D. H. A. Blank I. Vrejoiu M. Yoshimoto J.-P. Mosnier H. Fujioka S. Weißmantel	10:10 ————— Coffee Break 10:40 ————— XIV. Laser Plasma and Applications W. Husinski J. Schou D. Young 11:50 ————— Poster Award Closing Remarks 12:10 —————
15:00 ————— Registration 16:30 ————— Reception 19:00 —————	Coffee Break 16:00 ————— III. Pulsed Laser Deposition of Films T. Kobayashi H. -U. Habermeier R. Teghil I. Ohkubo P. R. Willmott E. Fogarassy R. K. Singh 18:40 —————	Coffee Break 16:30 ————— VI. Laser Processing: Modification, Etching, Cleaning, Machining M. Stuke M. C. Castex M. Meunier K. Sugioka Ph. Delaporte J. Gottmann 18:50 —————	19:00 ————— Banquet 21:00 —————	18:40 —————	